

Time for an Update

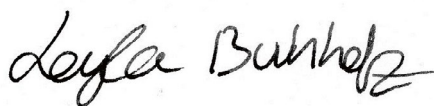
Dear Readers,

As you browse through this issue, you will notice: The layout of adhesion has been given a facelift. In times when print magazines are also being read more and more online, we decided it was time for a small update. We wanted to further improve the reader's guidance through the magazine in some places. Information should be easily accessible at a glance, and the issue should be faster and easier to navigate to the topics that are relevant to you. We hope you like the new look and appreciate your constructive criticism. The main topic of this issue is bonding in electronics manufacturing. In this context, you have probably heard of Moore's Law, a theory that the number of transistors on an integrated circuit doubles approximately every two years. This law is now outdated, as there are ever larger collections of chips with a higher functional density which put more and more stress on the solder joints. Reactive adhesives can help to alleviate them.

We also focus on adhesive processes in the packaging industry. The recyclability of packaging continues to be an important issue for packaging adhesives manufacturers regarding the Green Deal. According to the Packaging and Packaging Waste Regulation, packaging in the EU must have a certain minimum level of recyclability from 2030. Adhesives also play an important role here. For example, water-based adhesive systems can already be used in a variety of ways in flexible packaging. In PET/PE multilayer composites, water-based acrylate adhesives can be applied so that the two materials can be separated more easily after use and thus be recycled.

I wish you an interesting read.

Yours



Leyla Buchholz
Editor-in-Chief

